

2. (Amended) The method as defined in claim 6 wherein the thickness of the backside p⁺ emitter is approximately between 0.2 and 1 μm.

3. (Amended) The method as defined in claim 6 wherein the implanting dose of the backside p⁺ emitter is approximately between 1×10^{11} and 1×10^{17} cm⁻².

A' 4. (Amended) The method as defined in claim 6 wherein the thickness of the n-type residual diffused-layer contained in the n-type base is approximately between 5 and 50 μm.

B' Conf 5. (Amended) The method as defined in claim 6 wherein the doping concentration of the n-type residual diffused-layer is in a range of approximately $1 \times 10^{14} \sim 1 \times 10^{17}$ cm⁻³ at the interface of the residual layer and the backside p⁺ emitter.

6. A method for fabricating low-power-loss power semiconductor switching devices, wherein the fabrication is in the following sequence:

PROCEDURE I: fabricating a nonuniformly doped n-type substrate which contains a diffused n⁺ layer on one side, wherein the diffused layer, which is finally near to the backside p⁺ emitter, is formed in the first step of this procedure before the thinning of the substrate;

PROCEDURE II: fabricating the general frontside structure of either an IGBT, MCT, or GTO on the low-concentration side of the n-type substrate using ion implanting, high-temperature diffusion and so on;

PROCEDURE III: thinning the wafer from the high-concentration side of the substrate by such commonly used techniques as grinding and polishing, so that the thickness of the residual diffused-layer is decreased to a required value;